

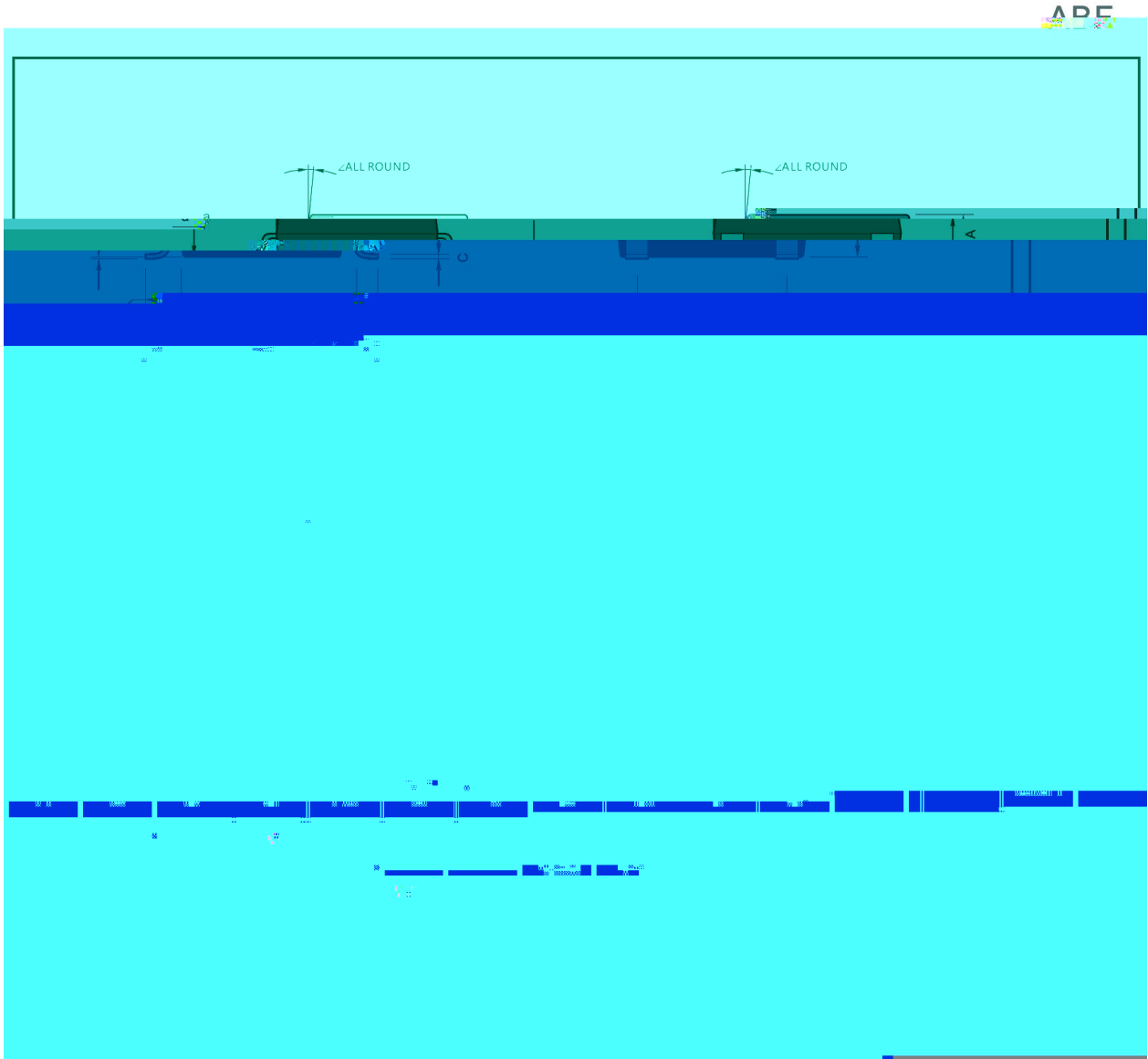
Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c = 125$	I_o	2.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	60	A
Typical Junction Capacitance ^{Note1}	C_j	40	pF
Typical Thermal Resistance ^{Note2}	R_{JA}	70	/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150	

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 1.0" X 1.0" (2.54 X 2.54 cm) copper pad.

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F=2.0A$	1.3	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5.0	A
		$T_a=125$	50	A <i>f</i>

/ Package Dimensions

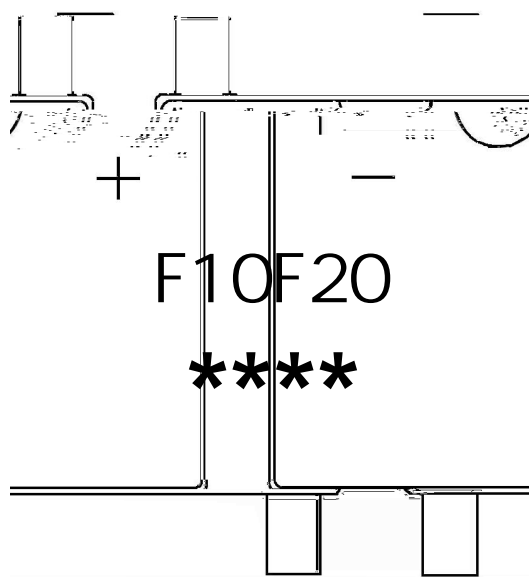


/ Marking Instructions

Marking



/ Marking Instructions



F10F20

1 *

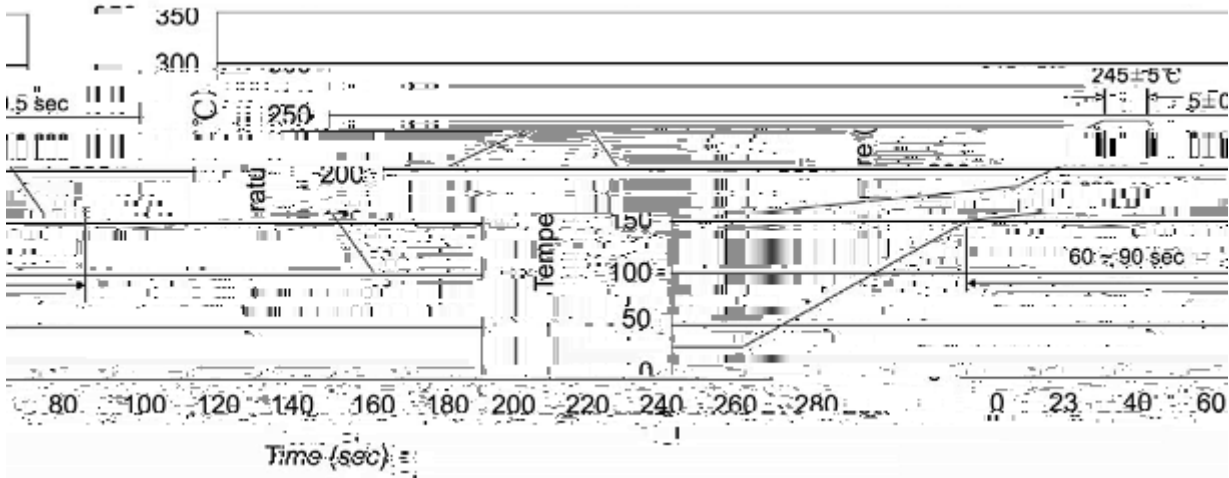
3 *

Note:

F10F20 Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot
No Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm ³)
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